

ABSTRACT

The object of the present invention is to assuredly merge adjacent coating liquid lines when a coating liquid is applied on a surface of a substrate by a so-called scan coating. The  
5 coating is performed while the wafer W is oriented to an orientation such that the scanning direction of the coating nozzle liquid 5 crosses all the dicing lines D formed on the wafer W. After completion of the application, the wafer W is returned to the original orientation, and thereafter the wafer W is  
10 unloaded from a coating film forming apparatus. The coating film forming apparatus stores a plurality of recipes defining coating conditions for each kind of wafer W. The coating conditions defined by the recipes include the orientation of the wafer W. The orientation of the wafer W is automatically set  
15 based on the selected recipe.